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# **IC Reliability Test Report**

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Customer information
Company:
Address:

#### **Purpose**

EKTA0200 high temperature operating life time test, for assessing the span of operating life, indicated by FIT or MTBF.

#### **Conclusion**

**EKTA0200** Reliability Test results: PASS

Approved by:

Check by:

Original by:



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## 1. General information

1.1 Description of Testing Samples

Product No: EKTA0200

#### 1.2 Execute Laboratory

Experiments are executed by QRA department of ELAN and the qualified unit (YTEC).

#### 1.3 Sampling Plan

The sampling plan is LTPD=5%.

#### 1.4 Pass/Fail Judgment

The final conclusion, 'pass' or 'fail' is judged from the FT test result with LTPD= 5%.

#### 1.5 Test Item

High temperature operating life time test. (HTOL)

#### 1.6 Method

1.HTOL (High Temperature Operation Life Test)

### 1.1 Sampling plan:

Sample size: 77 EA, based on LTPD= 5%, C= 1.

#### 1.2 Test Condition:

■ Vcc Applied Voltage: 3.6V

■ Environment Temperature : 125°C

■ TD (Duration): **1000hrs**, Test point at 168, 500, 1000hrs.

## 2. Test Item Summary

項 目	取樣	測試條件	完成日期	實驗結果	
Item	Sample size	Test condition	Finish date	Test Result	
High temperature operating life time test.	77	125°C, 1000hrs.	2022/06/27		



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## 3. Test Result

#### 3.1 HTOL Data

項 目	取樣	時間	不良數	FR	MTBF
Item	Sample size	Duration	No. of failure	(FIT)	(Hours)
High temperature operating life time test.	77	1000	0	3075	

#### 3.2 Calculation for test item 1.

Refer to the appendix 1 equation (5)

$$AF_T = \exp [Ea/K * (1/T o - 1/T s)]$$
 (5)

where

 $T \circ = 85^{\circ}\text{C}$  (358.16K), junction temperature at normal use condition.

 $T \text{ s} = 125^{\circ}\text{C}$  (398.16K), junction temperature under stress.

E a =0.7eV, For defects due to particle

 $k = 8.62 \times 10^{-5} \text{ eV/K}$  (the Boltzmann constant).

So the AF<sub>T</sub> is 9.7552...

And the predicted total device stressed hours is No \*  $T_H$  \*  $AF_T$ 

where

No = 77 ea

 $T_H = 1000 \text{ hours}$ 

 $AF_T = 9.7552...$ 

So the predicted total device stressed hours is 751150 (hours)

No device failed (N = 0), at confidence level of 90%, P = 2.31 for N = 0, then,

From the appendix1 equation (7)

$$P_{n}(1\text{-CL},2N+2)$$
 FR = ----\*10<sup>9</sup> (7) No \* T<sub>H</sub>\*AF

$$= (2.31*10^9) / (375575) = 3075 (FIT)$$

and the MTBF =  $1/FR = \frac{325174 \text{ (hours)}}{1}$